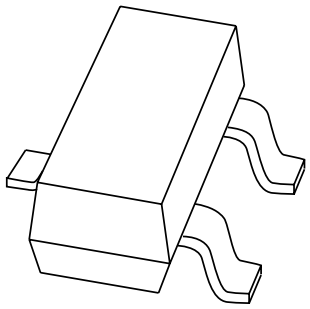
DATA SHEET



PBSS5130T

30 V, 1 A

PNP low V_{CEsat} (BISS) transistor

Product data sheet

2003 Dec 12

30 V, 1 A PNP low V_{CEsat} (BISS) transistor

PBSS5130T

FEATURES

- Low collector-emitter saturation voltage V_{CEsat}
- High collector current capability: I_C and I_{CM}
- Higher efficiency leading to less heat generation
- Reduced printed-circuit board requirements
- Cost effective alternative to MOSFETS in specific applications.

APPLICATIONS

- Power management
  - DC/DC converters
  - Supply line switching
  - Battery charger
  - LCD backlighting.
- Peripheral drivers
  - Driver in low supply voltage applications (e.g. lamps and LEDs)
  - Inductive load driver (e.g. relays, buzzers and motors).

DESCRIPTION

PNP low V_{CEsat} transistor in a SOT23 plastic package.

MARKING

TYPE NUMBER	MARKING CODE(1)
PBSS5130T	*3E

Note

1. * = p : made in Hong Kong
   * = t : made in Malaysia
   * = W : made in China.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V_{CEO}	collector-emitter voltage	–30	V
I_C	collector current (DC)	–1	A
I_{CRP}	repetitive peak collector current	–1.5	A
R_{CEsat}	equivalent on-resistance	220	mΩ

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector

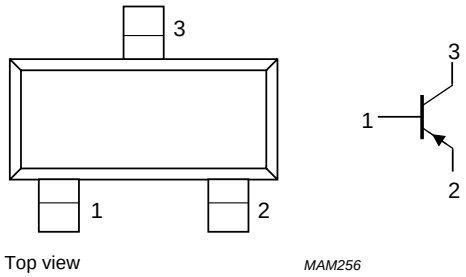


Fig.1 Simplified outline (SOT23) and symbol.

30 V, 1 A PNP low V_{CEsat} (BISS) transistor

PBSS5130T

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
PBSS5130T	–	plastic surface mounted package; 3 leads	SOT23

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	−30	V
V_{CEO}	collector-emitter voltage	open base	–	−30	V
V_{EBO}	emitter-base voltage	open collector	–	−5	V
I_C	collector current (DC)		–	−1	A
I_{CM}	peak collector current		–	−3	A
I_{BM}	peak base current		–	−300	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C			
		note 1	–	300	mW
		note 2	–	480	mW
T_{stg}	storage temperature		−65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	operating ambient temperature		−65	+150	°C

Notes

1. Device mounted on an FR4 printed-circuit board, single-sided copper, tinplated, standard footprint.
2. Device mounted on an FR4 printed-circuit board, single sided-copper, tinplated, mounting pad for collector 1 cm^2.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j\text{-}a}$	thermal resistance from junction to ambient	in free air		
		note 1	417	K/W
		note 2	260	K/W

Notes

1. Device mounted on an FR4 printed-circuit board, single-sided copper, tinplated and standard footprint.
2. Device mounted on an FR4 printed-circuit board, single-sided copper, tinplated and mounting pad for collector 1 cm^2.

CHARACTERISTICS

T_{amb} = 25 °C unless otherwise specified.

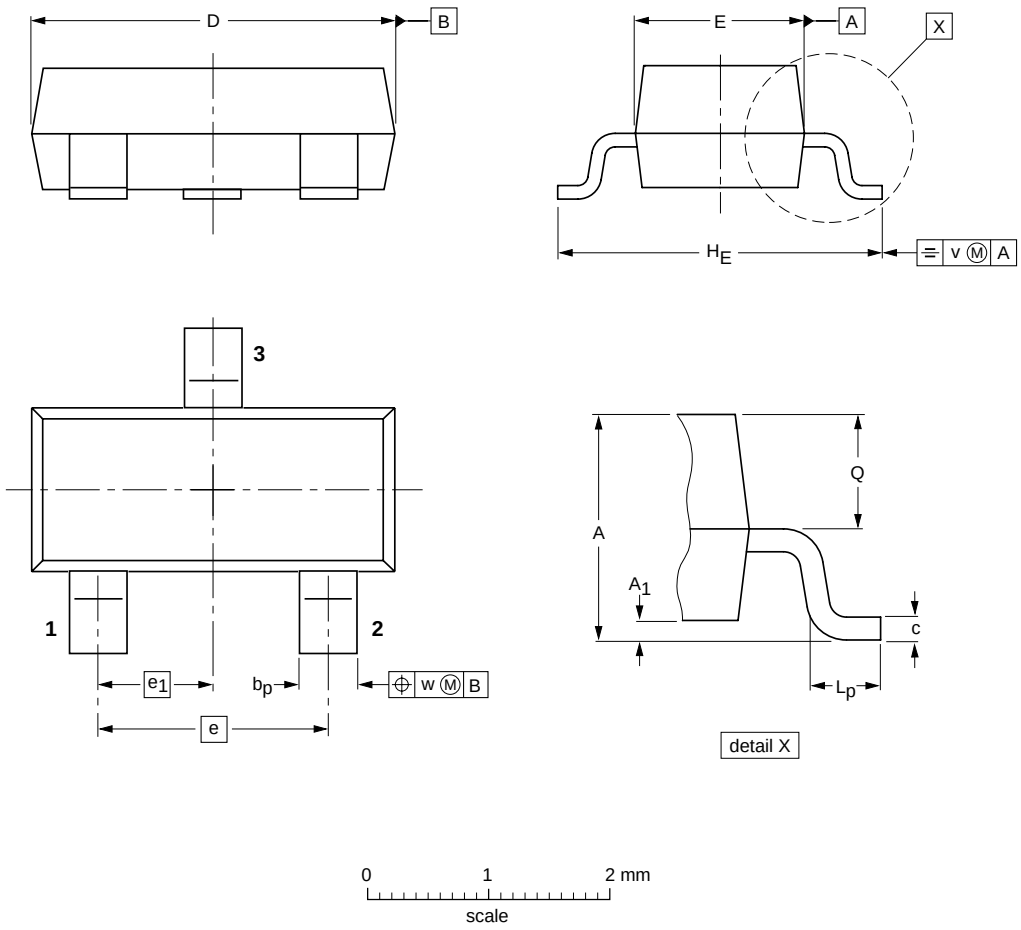
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector-base cut-off current	V_{CB} = –30 V; I_E = 0	–	–	–100	nA
		V_{CB} = –30 V; I_E = 0; T_j = 150 °C	–	–	–50	μA
I_{EBO}	emitter-base cut-off current	V_{EB} = –4 V; I_C = 0	–	–	–100	nA
h_{FE}	DC current gain	V_{CE} = –2 V; I_C = –100 mA	300	450	–	
		V_{CE} = –2 V; I_C = –500 mA	260	350	–	
		V_{CE} = –2 V; I_C = –1 A	210	290	–	
V_{CEsat}	collector-emitter saturation voltage	I_C = –100 mA; I_B = –1 mA	–	–	–100	mV
		I_C = –1 A; I_B = –50 mA	–	–	–225	mV
R_{CEsat}	equivalent on-resistance	I_C = –500 mA; I_B = –50 mA; note 1	–	–	220	mΩ
V_{BEon}	base-emitter turn-on voltage	V_{CE} = –2 V; I_C = –100 mA	–	–	–0.75	V
f_T	transition frequency	I_C = –100 mA; V_{CE} = –10 V; f = 100 MHz	100	200	–	MHz
C_c	collector capacitance	V_{CB} = –10 V; I_E = I_e = 0; f = 1 MHz	–	–	28	pF

Note

1. Pulse test: $t_p \leq 300$ μs; $\delta \leq 0.02$.

PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads **SOT23**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max.	b_p	c	D	E	e	e_1	H_E	L_p	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT23		TO-236AB				~~04-11-04~~ 06-03-16

DATA SHEET STATUS

DOCUMENT STATUS[1]	PRODUCT STATUS[2]	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

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